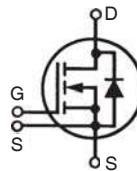


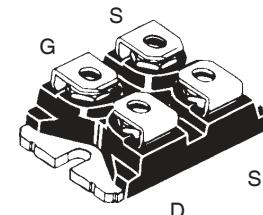
**X-Class HiPerFET™
Power MOSFET**
IXFN110N85X

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



V_{DSS} = 850V
I_{D25} = 110A
R_{DS(on)} ≤ 33mΩ

miniBLOC, SOT-227
 E153432



G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings		
V _{DSS}	T _J = 25°C to 150°C	850		V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	850		V
V _{GSS}	Continuous	± 30		V
V _{GSM}	Transient	± 40		V
I _{D25}	T _C = 25°C	110		A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	220		A
I _A	T _C = 25°C	55		A
E _{AS}	T _C = 25°C	3		J
P _D	T _C = 25°C	1170		W
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	50		V/ns
T _J		-55 ... +150		°C
T _{JM}		150		°C
T _{stg}		-55 ... +150		°C
V _{ISOL}	50/60 Hz, RMS I _{ISOL} ≤ 1mA	t = 1 minute t = 1 second	2500 3000	V~ V~
M _d	Mounting Torque Terminal Connection Torque	1.5/13 1.3/11.5	Nm/lb.in Nm/lb.in	
Weight		30		g

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 3mA	850		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 8mA	3.5		5.5 V
I _{GSS}	V _{GS} = ± 30V, V _{DS} = 0V			± 200 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			50 μA 5 mA
R _{DS(on)}	V _{GS} = 10V, I _D = 55A, Note 1			33 mΩ

Features

- International Standard Package
- miniBLOC, with Aluminium Nitride Isolation
- Isolation Voltage 2500V~
- High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Low R_{DS(on)}

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

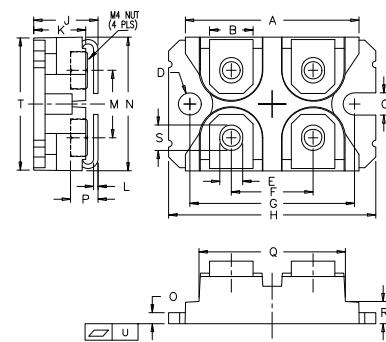
Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
I_{fs}	V _{DS} = 10V, I _D = 55A, Note 1	43	72	S
R _{Gi}	Gate Input Resistance		0.55	Ω
C _{iss}		17		nF
C _{oss}		16		nF
C _{rss}		260		pF
Effective Output Capacitance				
C _{o(er)}	Energy related } V _{GS} = 0V	470		pF
C _{o(tr)}	Time related } V _{DS} = 0.8 • V _{DSS}	2170		pF
t _{d(on)}		50		ns
t _r		25		ns
t _{d(off)}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 55A	144		ns
t _f	R _G = 1Ω (External)	11		ns
Q _{g(on)}		425		nC
Q _{gs}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 55A	105		nC
Q _{gd}		225		nC
R _{thJC}			0.107	°C/W
R _{thCS}		0.05		°C/W

Source-Drain Diode

Symbol	Test Conditions	Characteristic Values		
	(T _J = 25°C, Unless Otherwise Specified)	Min.	Typ.	Max.
I _s	V _{GS} = 0V		110	A
I _{SM}	Repetitive, Pulse Width Limited by T _{JM}		440	A
V _{SD}	I _F = I _S , V _{GS} = 0V, Note 1		1.4	V
t _{rr}		205		ns
Q _{RM}	I _F = 55A, -di/dt = 300A/μs	5.5		μC
I _{RM}	V _R = 100V, V _{GS} = 0V	54.0		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

SOT-227B (IXFN) Outline



(M4 screws (4x) supplied)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	.76	.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

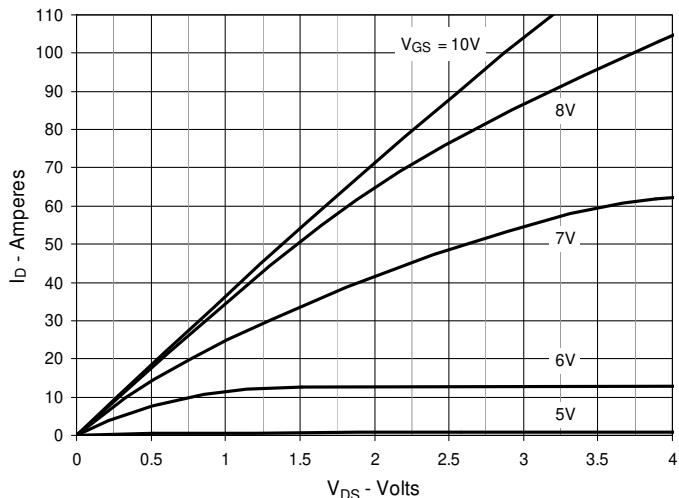
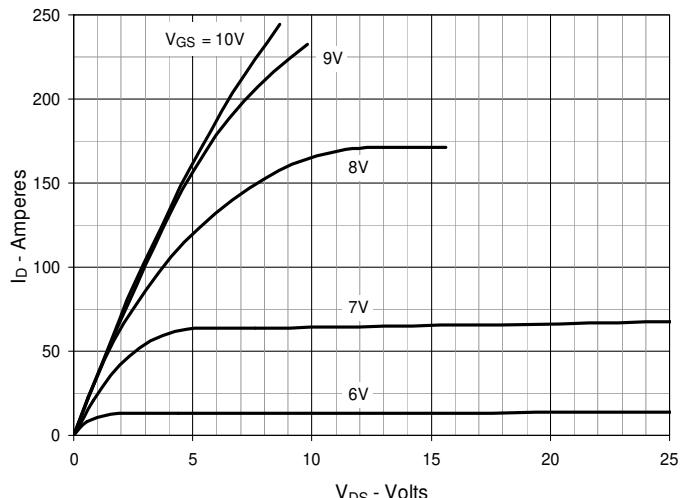
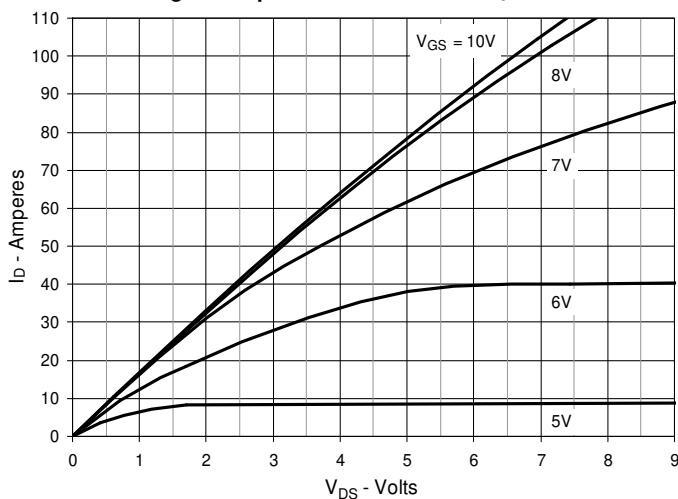
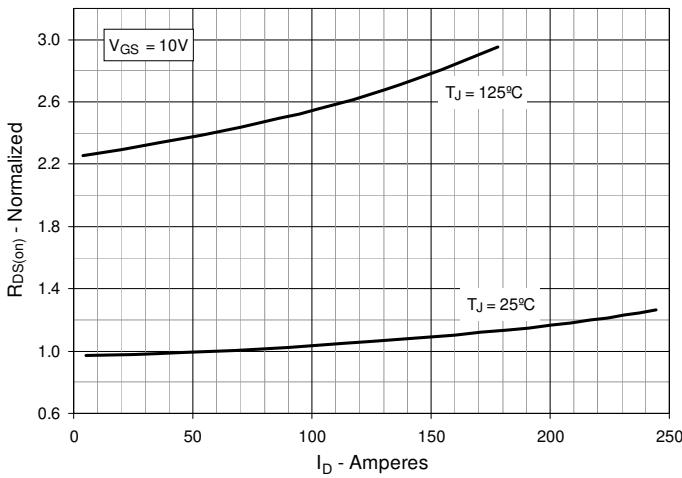
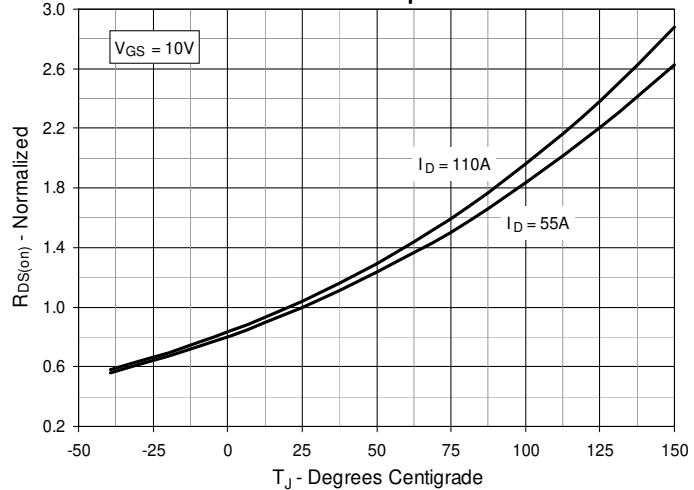
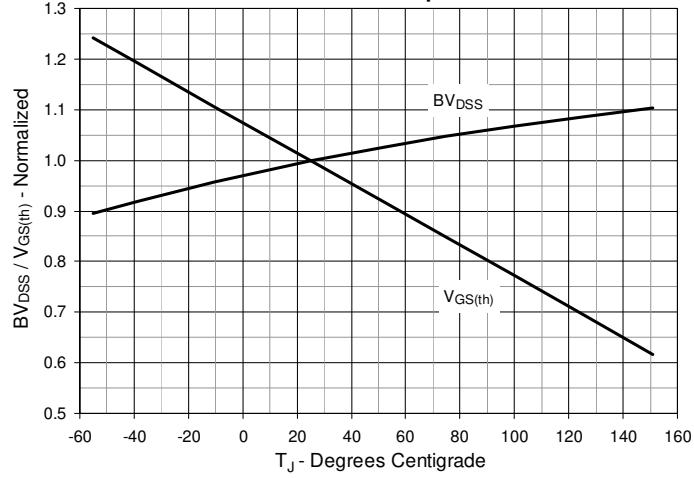
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 55\text{A}$ Value vs. Drain Current

Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 55\text{A}$ Value vs. Junction Temperature

Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature


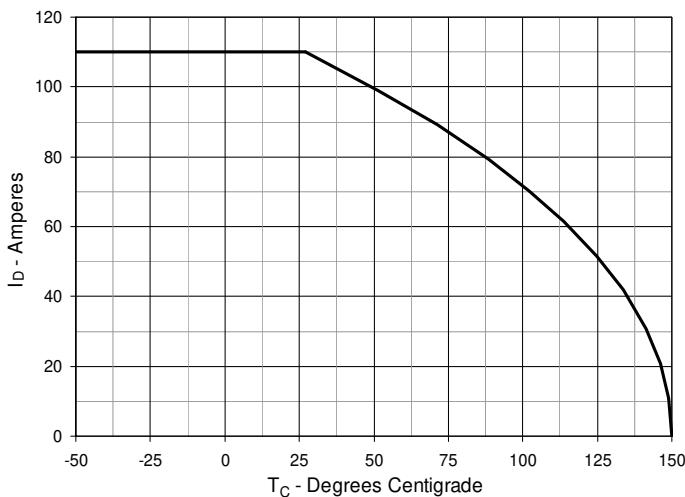
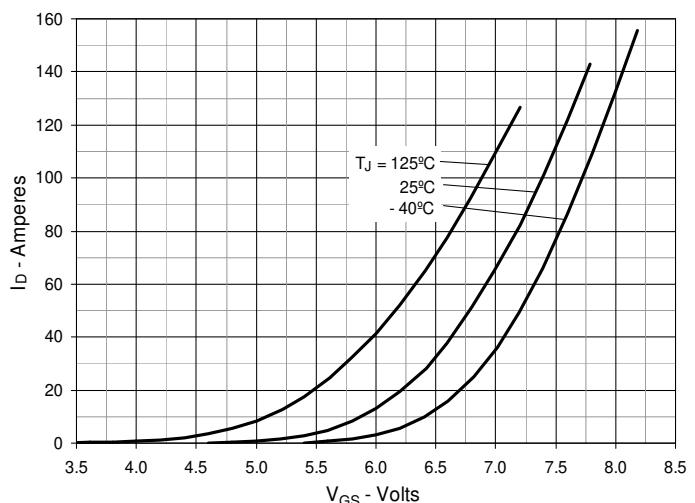
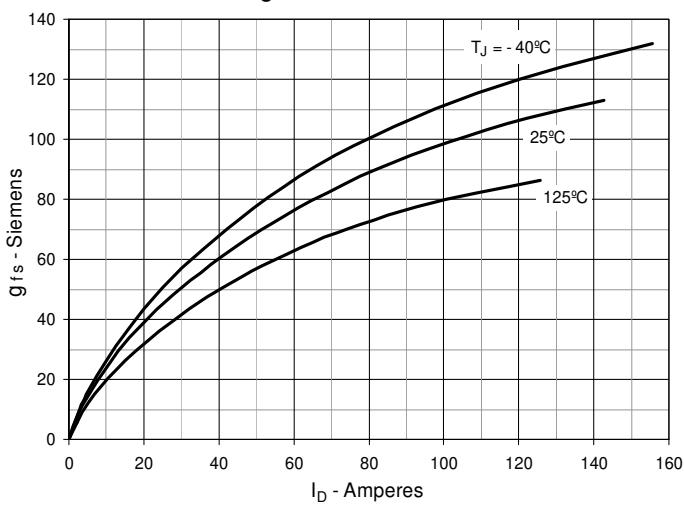
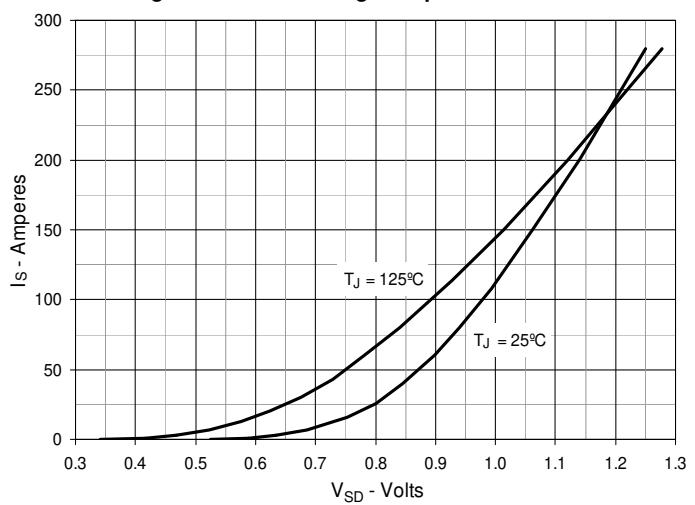
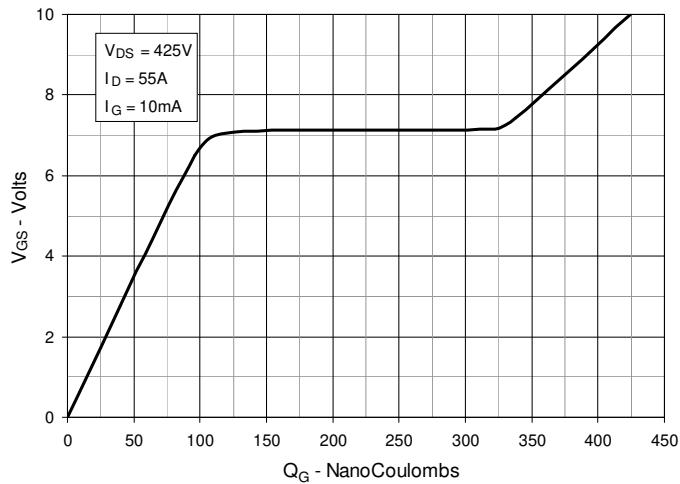
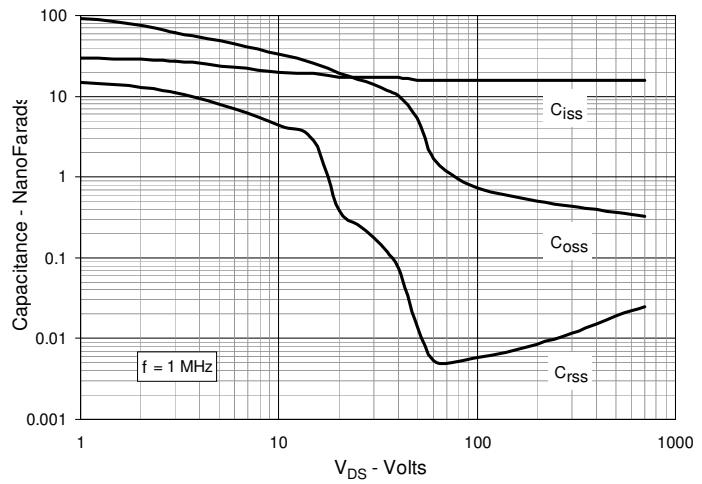
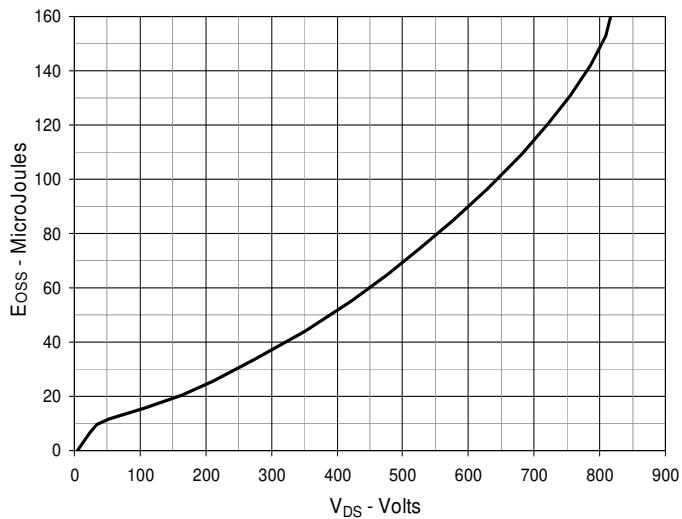
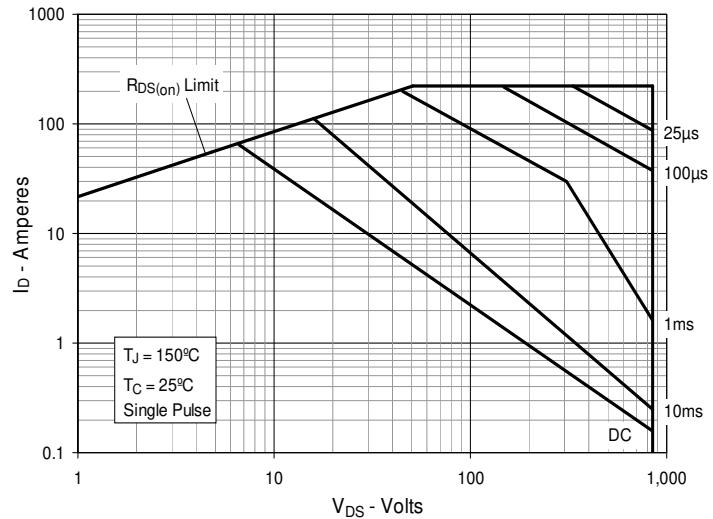
Fig. 7. Maximum Drain Current vs. Case Temperature**Fig. 8. Input Admittance****Fig. 9. Transconductance****Fig. 10. Forward Voltage Drop of Intrinsic Diode****Fig. 11. Gate Charge****Fig. 12. Capacitance**

Fig. 13. Output Capacitance Stored Energy**Fig. 14. Forward-Bias Safe Operating Area****Fig. 15. Maximum Transient Thermal Impedance**